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ADVANCED IC PACKAGING TECHNOLOGIES, MATERIALS, AND MARKETS

2011 EDITION

**A Strategic Report on the Latest
Technologies in IC Packaging
With Forecasts of Key Markets**

Report Coverage

- **Stacked Packages**
- **Through Silicon Vias (TSV)**
- **System in Package (SiP)**
- **Fan-in QFN**
- **WLPs including Fan-out Style**
- **Interconnect and Bumping**
- **Substrates**
- **Wire Bonds**

Report Highlights

- **Technology Updates**
- **Research News**
- **New Products Introductions**
- **Industry Outlook**
- **End Markets/Applications**
- **Market Analysis and Forecasts,
2010–2015**

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Synopsis

Despite a global recession, the demand for handheld portable products remains strong. To continue to meet the ever-increasing needs for higher bandwidth, IC packaging technologies are continually being pushed to the limit. This report details the advances in those limits.

New Venture Research (NVR) in its report, **Advanced IC Packaging Technologies, Materials, and Markets, 2011 Edition**, uses information from IC packaging industry insiders to present the most realistic forecasts available regarding advanced IC packaging. Throughout the report, the latest advanced packaging products, services, and research from numerous companies and organizations are described.

Chapter 3, Stacked Packages, explains the basics of this critical packaging technology, along with a sampling of the latest products. Forecasts include units, prices, packaging revenue, package types, device types, first-level interconnection, and applications.

Chapter 4, TSV Market (3D and 2.5D stacking) is covered in depth, including various methods of connecting the devices, specific company applications, and numerous examples of the latest new products and processes. Unit projections are forecast and an examination of the markets which are incorporating this technology first are included.

Chapter 5, System in Package (SiP) Solutions, presents information on the evolving market for ICs combined with passive devices within a single package. Forecasts include units, prices, packaging revenue, device types, interconnection, and applications.

Chapter 6, Fan-in QFN Packages, examines the latest new product introductions plus market forecasts for Fan-in QFN Packages. Forecasts include units, prices, packaging revenue and applications.

Chapter 7, Wafer-Level Packages Including Fan-out Style, explains the latest new product introductions plus market forecasts for WLP by product, pitch and re-configured wafer-level packages.

Chapter 8, Interconnection, Wire Bond, Flip Chip, and Bumping, contains a review of first-level package interconnection. Revenue and unit forecasts of wirebond and flip chip interconnection are provided for PGA, BGA, and FBGA packages, plus wire bond material by wire width. Unit forecasts are provided for total flip chip interconnection, both in package and as direct chip attach (DCA), bump styles, and UBM processes.

Chapter 9, Substrates, presents the market, including an overview of substrate types and materials, and highlights of recent developments in substrates. Forecasts are provided for substrate units, area, and revenue by package type and substrate material, and package pitch for PGA, BGA and FBGA.

Chapter 10, Mobile Applications for IC Devices, presents product applications such as cellular handsets and infrastructure, tablets, set-top boxes, DVD players/recorders, digital cameras/ camcorders, personal navigation, audio products, notebook/netbooks and PCs, servers and workstations.

Trends in advanced IC packaging are important to your business. **Advanced IC Packaging Technologies, Materials, and Markets - 2011 Edition** will provide you with an effective and economical tool for assessing the future of this market. The report sells for \$2995 as a single-user license PDF file. Additional licenses sell for \$250 each and a corporate license sells for \$1000. With the purchase of the report, an Excel spreadsheet of all tables may be obtained for an additional \$500.

About the Author

Sandra Winkler is the senior analyst for IC packaging at **New Venture Research (NVR)**. She began her analyst career as an independent consultant to the telecommunications industry over 20 years ago. Since 1995, Ms. Winkler has authored all of NVR's widely cited reports on IC packaging. She has spoken at numerous industry conferences, writes columns for Chip Scale Review magazine and contributes articles to the IEEE CPMT SCV Chapter Newsletter. Ms. Winkler is a senior member of IEEE/CPMT and serves on the executive committee for the IEEE-CPMT-SCV chapter where she is also the Program Co-Chair. She holds a MBA from Santa Clara University.

Table of Contents

Chapter 1: Introduction

Chapter 2: Executive Summary

Chapter 3: Stacked Packages

- Types of Stacked Packages
- The Ins and Outs of Stacked Packages Interconnection
- Stacked Package as a Multicomponent Package
- Wafer Thinning
- End Markets and Application Trends
- New Product Introductions
- Stacked Package Forecasts
- Stacked Packages by Application
- End Markets for Stacked Packages
- Potential Markets
- Stacked Packages by Device Type
- Stacked Packages by Interconnection

Chapter 4: Through Silicon Via (TSV) Market

- Overview
- Creating the Vias
- Issues
- 3D Die-Stacking Technology Requirements
- 2.5D - Silicon Interposers and Microbumps
- Wafer-to-Wafer Bonding
- Die-to-Wafer Bonding
- Die-to-Die Bonding
- Via First, Middle, or Last Technology
- Via Etching and Filling
- Specific Company Applications
- Companies with TSV Designs
- New Product Highlights
- Advances in Test
- Moving Forward
- Industry Consortia
- Market Potential
- Forecasts for 2.5D and 3D

Chapter 5: System in Package (SiP) Solutions

- Overview
- New Product Introductions/Highlights
- SiP Forecasts
 - Summary
 - SiPs by Application
 - SiPs by Device Type
 - SiPs by Interconnection

Chapter 6: Fan-in QFN Packages

- Overview
- New Product Introductions
- Market Forecasts

Chapter 7: Wafer-Level Packages including Fan-out WLPs

- Wafer-Level Package Overview
- New Product / Process Introductions
- Market Forecasts for WLP
- Forecasts by Product
- Forecasts by Pitch
- Forecasts of Fan-out WLP

Chapter 8: Interconnection, Wire Bond, Flip Chip and Bumping

- Interconnection Overview
- Wire Bonding
- Flip Chip
- TAB
- Wafer-Bumping and Process Overview
- Alternatives to Solder
- Product Highlights
- Flip Chip Applications
- Forecasts for:
 - Interconnect by Package Units
 - Wire Bond Package Units and Materials
 - Flip Chip
 - Flip Chip Bumps
 - UBM Process Techniques
 - Total Wire Bond and Flip Chip

Chapter 9: Substrates

- Overview
- Ceramic
- Laminate
- HDIS
- Flex Tape
- Embedded Passives
- Thermal Substrates
- Product Highlights
- Forecasts
- Units by Pitch
- Units, Area, Revenue by Package Family
- Units, Area, Revenue by Material

Chapter 10: State of the Industry and Applications for Mobile Devices

- Overview of Current Market Status
- Mobile Electronic Applications for IC device by Product Group
- Total IC for each Product Category
- Total IC Revenue

Table of Contents (continued)

Partial List of Figures and Tables

Dual-Die TSOP Stack
STATS ChipPAC's PiP
High Performance Stakpak
DAG Process Steps
Dice Before Grinding Method
Die Thickness Relative Strength
8-Gigabit TSV DRAM Package Outline and Cross Section
A Schematic Illustration Showing the CoW Bonding Process
Micro-Bump and UMB Pad Structure
Die Stack FBGA Packages, 2010-2015
PoP Packages, 2010-2015
PiP Packages, 2010-2015
TSOP Stacked Packages, 2010-2015
QFN Stacked Packages, 2010-2015
MCM Stacked Packages
Stacked WLPs, 2010-2015
Stacked Package Assembly Revenue, 2010-2015
Total ICs in Stacked Packages, 2010-2015
Stacked ICs as a Percentage of Total ICs, 2010-2015
Stacked Packaging Revenue as a Percentage of Total Packaging Revenue, 2010-2015
Application Breakdown for Stacked Packages, 2010
Cellular Handsets vs. Stacked Packages, 2010-2015
Market for Various End Products Using Stacked Packages
Total Memory Devices in FBGAs
Total Memory Devices in WLPs
Stacked Packages by Device Type
Interconnection of Stacked Packages, 2010-2015
SiPs, 2010-2015
SiPs by Device Type, 2010-2015
Interconnection of SiPs, 2010-2015
Applications for SiPs, 2010
QFN Interconnection Forecast, 2010-2015
PGA Interconnection Forecast, 2010-2015
BGA Interconnection Forecast, 2010-2015
FBGA Interconnection Forecast, 2010-2015
Total Flip Chip Forecast, 2010-2015
Flip Chip Bump Styles, 2010-2015
UBM Process, 2010-2015
Bump Composition Units, 2010-2015
Devices in QFN Packages
Array QFN Forecast, 2010-2015

Advanced IC Packaging Technologies, Materials, and Markets, 2011 Edition

Table of Contents (continued)

The latest advanced packaging products, services, and research of the following companies and organizations are interspersed throughout the report:

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